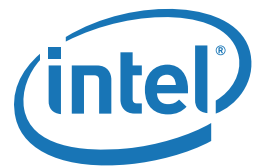


BPC-Q370-3L/BPC-H310-3L

Fanless Embedded PC Powered by Q370/H310 Chipset supporting Intel 8th & 9th Gen. Core i3/i5/i7/Pentium/Celeron Processors



- Intel Q370/H310 Chipset, supporting 8th, 9th Gen. i3/i5/i7 /Pentium/Celeron CPU (Max.TDP 35W)
- Dual channel DDR4 RAM up to 32GB
- 3 x Intel Gigabit Lan
- 4 x COM ports (2 x RS232/422/485)
- 4 x USB3.1(4 x USB3.0 for H310), 2x USB2.0
- 3 x M.2 interface for SSD, Wi-Fi and 4G module
- 2 x DP, 1 x DVI-D
- 12V 5A DC input
- Wide Temperature Optional



Introduction

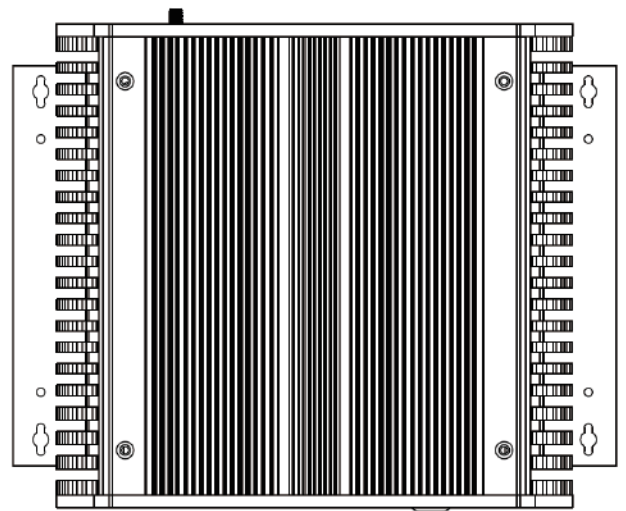
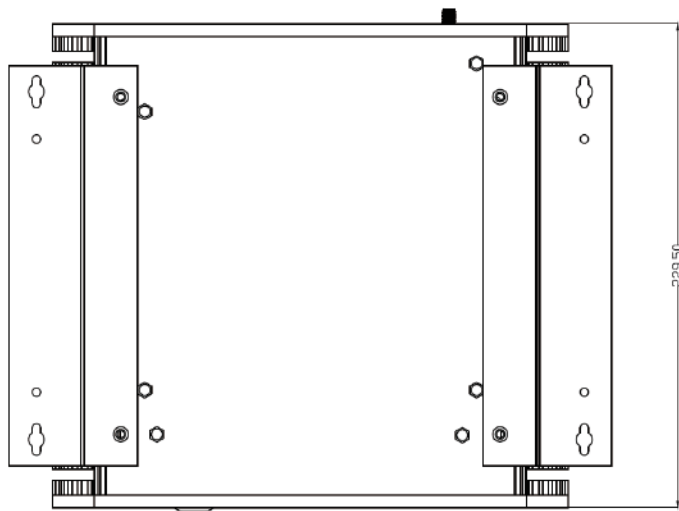
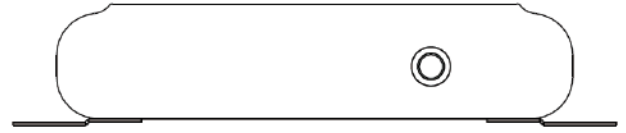
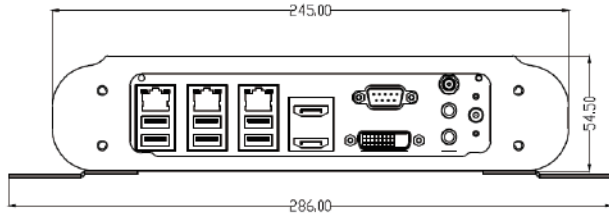
BPC-Q370-3L/BPC-H310-3L is an compact and powerful embedded fanless pc designed for reliable operation in a range of industrial applications. This pc is equipped with new generation ICEFIN fanless design, achieving outstanding cooling performance under high load 24*7 operations.

With up to 32 GB of DDR4 memory, the system is powerful enough to serve as a high-end workstation with a footprint considerably smaller than a traditional desktop PC. With multiple I/O extension, the BPC-Q370-3L/BPC-H310-3L fits right into both commercial and industrial applications, including: 4 COM ports(2 supporting RS232/422/485 and 2 for RS232), 4 USB3.1(4 x USB3.0 for H310), 2 USB2.0, 2 DP and 1 DVI-D. It also has 3 ethernet and supports for optional 4G LTE connectivity, enabling easy remote network access.

Technical Specifications

Core System	Processor	Intel® 8th/9th Gen. Core i3/i5/i7/Pentium/Celeron CPU (Max.TDP 35W)
	Chipset	Intel® Q370/H310 Chipset
	Supported CPU Models	Intel Celeron CPU: G4900T/G4930T Intel Pentium Gold CPU: G5400T/G5420T/5500T/G5600T Intel 8th Gen. CPU: Core i3-8100T/i3-8300T/i5-8400T/i5-8500T/i5-8600T/i7-8700T Intel 9th Gen. CPU: Core i3-9100TE/i3-9100T/i3-9300T/i5-9400T/i5-9500T/i5-9500TE/i5-9600T/i7-9700T/i7-9700TE
	Memory	Dual-channel DDR4 SO-DIMM memory, max to 32GB
	SSD	1 x M.2 2280/42, support PCIe SSD
	HDD	1 x 2.5" Drive Bay(Optional)
External Connectors	Ethernet	3 x Intel® Gigabit LAN (1 x I219 + 2 x I210)
	USB	4 x USB3.1(4 x USB3.0 for H310), 2 x USB2.0
	Serial Ports	1 x COM (COM1 for RS232)
	Display	2 x DP++, 1 x DVI-D support 4K x 2K@60Hz Triple independent display for Q370 chipset. Dual independent display for H310 chipset
	Audio	1 x Mic-in, 1 x Line-out
Expansion Slots	Expansion	1 x M.2 KEY-A supports WIFI, BT, 1 x M.2 KEY-B supports 4G
		3 x COM(COM2 for RS232, COM3/COM4 for RS232/RS485/RS422)
		1 x USB3.0 pin, 2 x USB2.0 pin (No USB/USB3.0 for H310)
		1 x PCIe X16 slot, 1 x PCIe X4 slot (No PCIe X4 for H310)
		4 x SATA 6Gbps(2 for H310)
Mechanical & Environmental	Mounting	Wall mounting or Desktop (VESA mounting optional)
	System Control	Power switch
	Power Supply	DC 12V 5A power adapter
	Operating Temp.	-20C° ~ 60C° (-40C° ~ 85C° Optional)
	Storage Temp.	-40C° ~ 85C°
	Humidity	5% ~ 95%, non condensing
	Working Vibration	0.5g rms/5~500Hz/random operating
	Color	Black
	Size	245mm x 194mm x 54.5mm (W x D x H)
	Cooling System	Fanless, ICEFIN cooling system
	Structure	New generation ICEFIN enclosure
	Texture	Aluminum alloy

Structural Diagram



Front view



Back view



ABOUT POLYHEX

As a board level and system level designer and manufacturer, Polyhex, with 9 years' experience, always delivers best-in-class embedded computing solutions based on both ARM and X86 architecture, including hardware customization and software debugging etc. Partnered with silicon vendors like Intel, NXP, ST, Rockchip, Allwinners and so on, we have earned trust from clients worldwide in over 30 countries. Polyhex is also certified with ISO9001 and ISO13485 for the self-owned manufacture facility.

